





Power MOSFETS


DATASHEET

LM1AA60NAJ3A

N-Channel
Enhancement Mode MOSFET

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Quality Management Systems

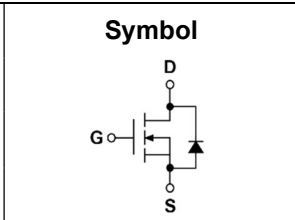
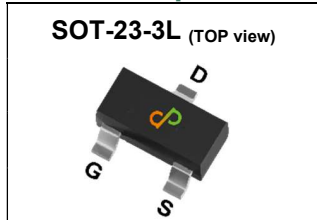
ISO 9001:2015 Certificate

LM1AA60NAJ3A



N-Channel Enhancement Mode MOSFET

Pin Description



Product Summary

Symbol	N-Channel	Unit
V_{DSS}	100	V
$R_{DS(ON)-Max}$	160	m Ω
I_D	2.8	A

Feature

- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Applications

- Synchronous Rectifiers for SMPS
- LED Backlighting

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM1AA60NAJ3A	SOT-23-3L	Tape & Reel	3000 / Tape & Reel	01□□□

Note : □□□ = Lot Code

Absolute Maximum Ratings (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit	
V_{DSS}	Drain-Source Voltage	100	V	
V_{GSS}	Gate-Source Voltage	±20		
T_J	Maximum Junction Temperature	150	°C	
T_{STG}	Storage Temperature Range	-55 to 150	°C	
$I_{DM}^{①}$	Pulse Drain Current Tested	$T_A=25^{\circ}C$	7	A
I_D	Continuous Drain Current	$T_A=25^{\circ}C$	2.8	A
		$T_A=70^{\circ}C$	2.2	
P_D	Maximum Power Dissipation	$T_A=25^{\circ}C$	1.25	W
		$T_A=70^{\circ}C$	0.8	
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.1mH	8	A
		L=0.5mH	4.5	
$E_{AS}^{③}$	Avalanche Energy, Single pulse	L=0.1mH	3.2	mJ
		L=0.5mH	5	

Thermal Characteristics

Symbol	Parameter	Rating	Unit	
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	Steady State	100	°C/W

Note ① : Max. current is limited by junction temperature.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

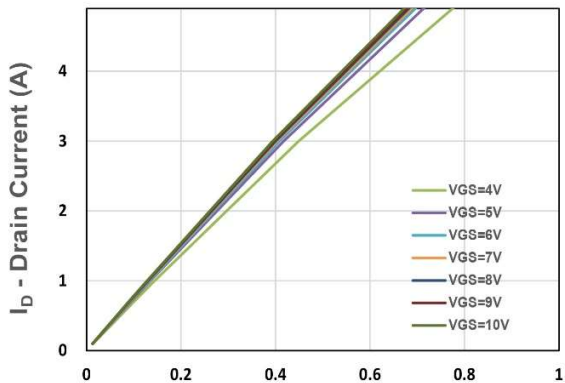
N-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250uA	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V	-	-	1	uA
V_{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250uA	1.0	1.9	3.0	V
I_{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R_{DS(ON)} ^④	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =1A	-	130	160	mΩ
		V _{GS} =4.5V, I _{DS} =0.5A	-	140	180	
gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =1A	-	4.5	-	S
Dynamic Characteristics ^⑤						
R_G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Freq.=1MHz	-	5.4	-	Ω
C_{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =50V, Freq.=1MHz	-	451	-	pF
C_{oss}	Output Capacitance		-	32	-	
C_{rss}	Reverse Transfer Capacitance		-	18	-	
td(ON)	Turn-on Delay Time	V _{GS} =10V, V _{DS} =50V, I _D =1A, R _{GEN} =6Ω	-	10	-	nS
t_r	Turn-on Rise Time		-	8	-	
t_{d(OFF)}	Turn-off Delay Time		-	30	-	
t_f	Turn-off Fall Time		-	5	-	
Q_g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =50V I _D =1A	-	4.16	-	nC
Q_g	Total Gate Charge	V _{GS} =10V, V _{DS} =50V, I _D =1A	-	8.4	-	
Q_{gs}	Gate-Source Charge		-	1.1	-	
Q_{gd}	Gate-Drain Charge		-	1.5	-	
Source-Drain Characteristics						
V_{SD} ^④	Diode Forward Voltage	I _{SD} =1A, V _{GS} =0V	-	0.75	1.1	V
t_{rr}	Reverse Recovery Time	I _F =1A, V _R =50V	-	20	-	nS
Q_{rr}	Reverse Recovery Charge	dI _F /dt=100A/μs	-	12.4	-	nC

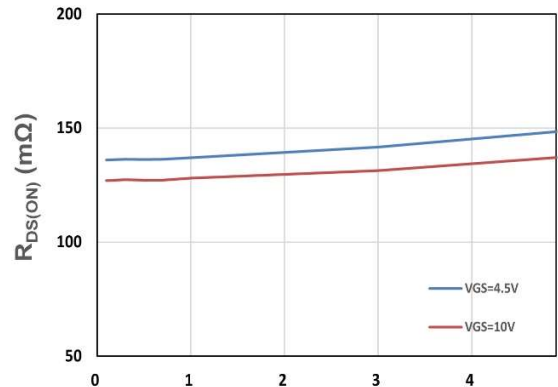
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

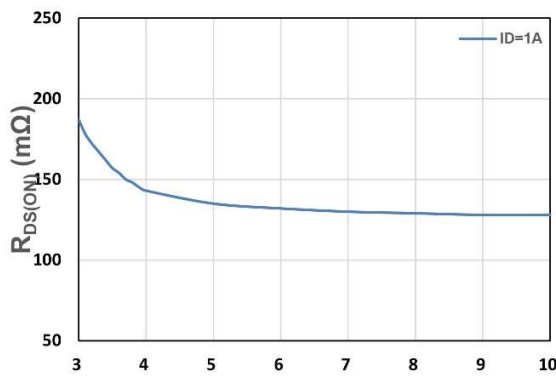
N-Channel Typical Characteristics



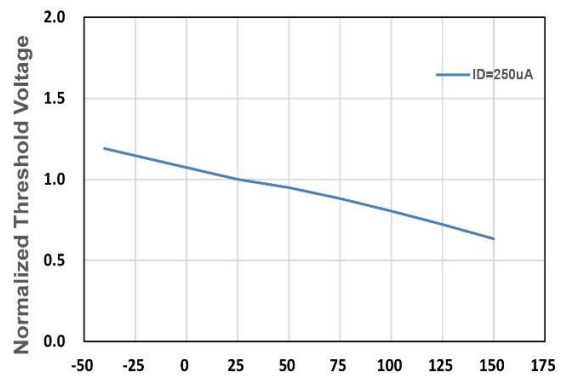
V_{DS} - Drain - Source Voltage (V)
Figure 1. Output Characteristics



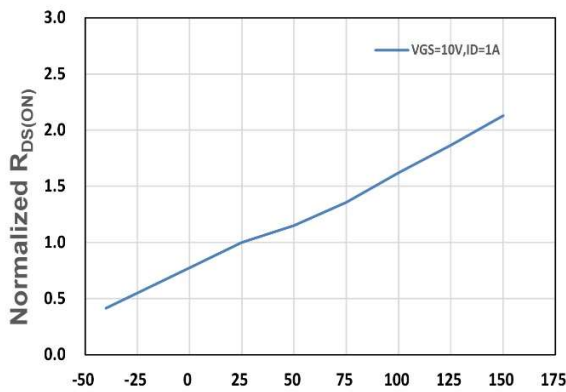
I_D - Drain Current (A)
Figure 2. On-Resistance vs. ID



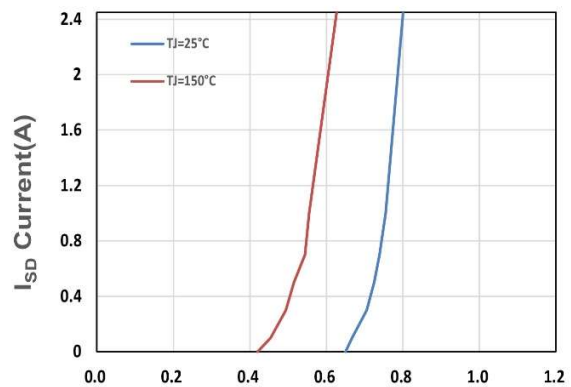
V_{GS} - Gate - Source Voltage (V)
Figure 3. On-Resistance vs. VGS



T_j , Junction Temperature(°C)
Figure 4. Gate Threshold Voltage



T_j , Junction Temperature(°C)
Figure 5. Drain-Source On Resistance



V_{SD} , Source-Drain Voltage(V)
Figure 6. Source-Drain Diode Forward

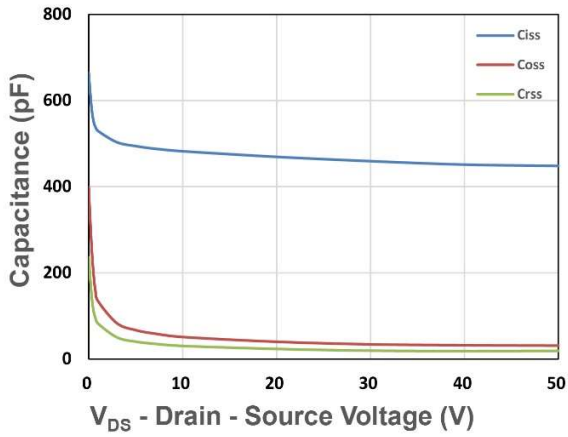


Figure 7. Capacitance

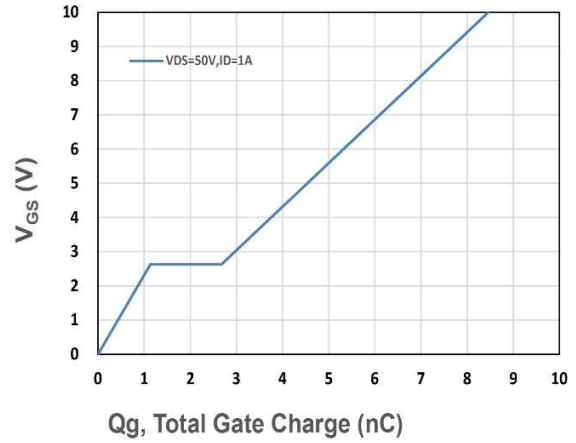


Figure 8. Gate Charge Characteristics

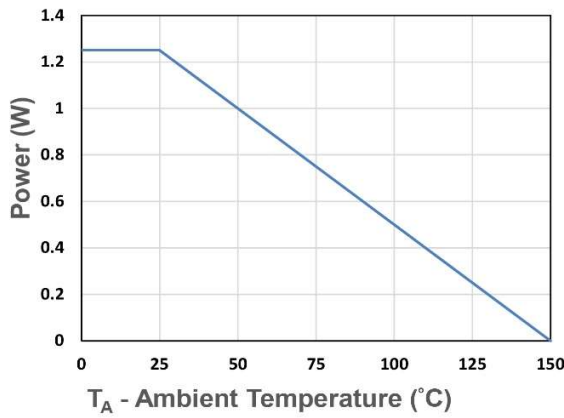


Figure 9. Power Dissipation

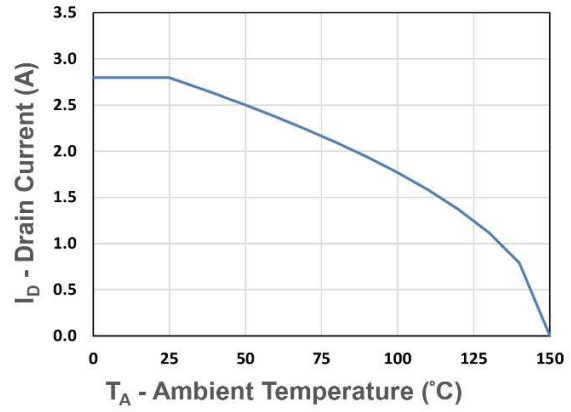


Figure 10. Drain Current

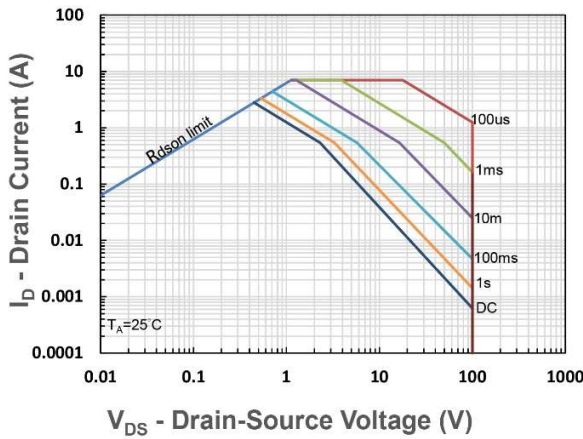


Figure 11. Safe Operating Area

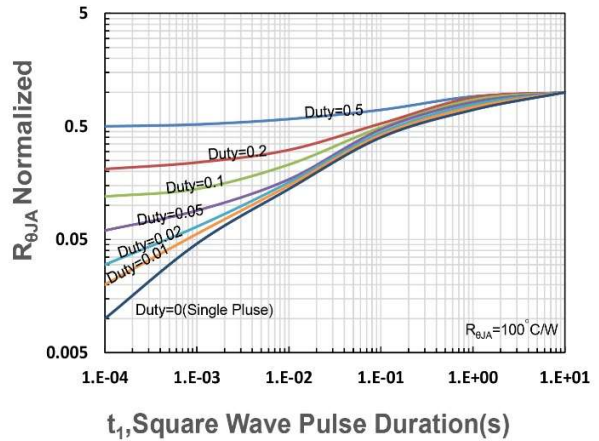


Figure 12. $R_{\theta JA}$ Transient Thermal Impedance